



2019

Electronic Design Innovation Conference
电子设计创新大会

April 1-3, 2019

China National Convention Center

Beijing, China

Host Sponsor:



Diamond Sponsor:



Organized by:



EDICONCHINA.com

China's Largest RF/Microwave and High-Speed Digital Conference & Exhibition

Where High Frequency Meets High Speed

EDI CON China celebrates electronic design innovation, bringing together RF, microwave, EMC/EMI, and high-speed digital design engineers and system integrators for networking, training, and learning opportunities. Attendees come to EDI CON to find solutions, products, and design ideas that they can put into immediate practice for today's communication, defense, consumer electronics, aerospace, and medical industries.

Drawing attendees working on analog and digital designs, EDI CON enables designers to see techniques and technologies used in other applications that could be applied or adapted to solve their latest design challenges. The exhibition features product displays, demonstrations, networking opportunities, and poster sessions that address all aspects of design, simulation, test, and verification.

Conference Technical Sessions

The EDI CON 20-minute technical sessions are educational, providing practical information on how to address today's design challenges using available materials, tools, products, and techniques. Divided into technical tracks, the sessions focus on a range of high frequency and high-speed electronic design issues from modeling and design through to characterization and system integration. Abstracts and papers are submitted through the Call for Abstracts process.

Sponsored Workshops

The 40-minute sponsored EDI CON workshops allow industry experts to share information on specific challenging and emerging topics related to high frequency or high speed electronic design. Workshops are an interactive experience, allowing time for audience questions and may include demonstrations of design software and/or measurement equipment. Sponsors are responsible for workshops content according to the guidelines set by the EDI CON organizers. Sponsors receive full contact leads of session attendees.

Global Exhibition

Showcase your company's products and services to key decision makers and qualified buyers with your booth on the exhibition floor. Sponsorships and booth costs are:

Gold Sponsor (Limited to 6)	Silver Package	Bronze Package	Exhibit Only
36 square meter booth	18 square meter booth*	9 square meter booth*	9 square meter booth*
70 VIP Passes	60 VIP Passes	50 VIP Passes	
Two 40-minute workshops	One 40-minute workshop	One 40-minute workshop	
Listing on signage & select promotional material	Listing on signage & select promotional material	Listing on signage & select promotional material	
\$ 20,000 (USD)	\$ 13,000 (USD)	\$ 8,000 (USD)	\$ 3,500/per
<small>* Shell scheme includes carpet, signage, table and 2 chairs</small>			

For details on EDI CON 2019, contact:

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